

Automotive 750 V, 600 A Dual Side Cooling Half-Bridge Power Module

VE-Trac™ Dual Gen II NVG600A75L4DSC2

Product Description

The NVG600A75L4DSC2 is part of a family of power modules with dual side cooling and compact footprints for Hybrid (HEV) and Electric Vehicle (EV) traction inverter application.

The module consists of two narrow mesa Field Stop (FS4) IGBTs in a half-bridge configuration. The chipset utilizes the new narrow mesa IGBT technology in providing high current density and robust short circuit protection with higher blocking voltage to deliver outstanding performance in EV traction applications.

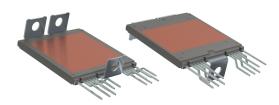
Liquid cooling heatsink reference design, loss models and CAD models are available to support customers in inverter designs.

Features

- Dual-Side Cooling
- Integrated Chip Level Temperature and Current Sensor
- $T_{vi max} = 175$ °C for Continuous Operation
- Low-Stray Inductance
- Low Conduction and Switching Losses
- Automotive Grade
- 4.2 kV Isolated DBC Substrate
- AEC Qualified and PPAP Capable
- This Device is Pb-Free and is RoHS Compliant

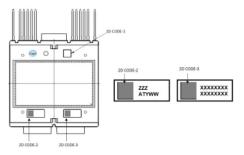
Typical Applications

- Hybrid and Electric Vehicle Traction Inverter
- High Power DC-DC Boost Converter



AHPM15-CEA CASE MODHS

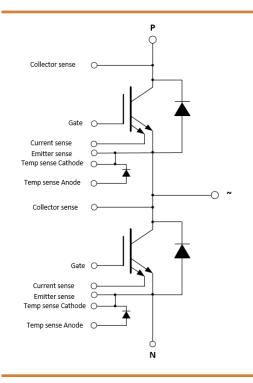
MARKING DIAGRAM



ZZZ = Assembly Lot CodeAT = Assembly & Test Location

Y = Year WW = Work Week

XXXX = Specific Device Code



ORDERING INFORMATION

See detailed ordering and shipping information on page 5 of this data sheet

PIN DESCRIPTION

Pin#	Pin	Pin Function Description	Pin Arrangement
1	N	Low Side Emitter	2
2	Р	High Side Collector	, ,
3	H/S COLLECTOR SENSE	High Side Collector Sense	3 0
4	H/S CURRENT SENSE	High Side Current Sense	I
5	H/S EMITTER SENSE	High Side Emitter Sense	6 -
6	H/S GATE	High Side Gate	4 0 5
7	H/S TEMP SENSE (CATHODE)	High Side Temp sense Diode Cathode	7 0 1
8	H/S TEMP SENSE (ANODE)	High Side Temp sense Diode Anode	9
9	~	Phase Output	15 0
10	L/S CURRENT SENSE	Low Side Current Sense	
11	L/S EMITTER SENSE	Low Side Emitter Sense	12 0
12	L/S GATE	Low Side Gate	10 0
13	L/S TEMP SENSE (CATHODE)	Low Side Temp sense Diode Cathode	13 0
14	L/S TEMP SENSE (ANODE)	Low Side Temp sense Diode Anode	14 0
15	L/S COLLECTOR SENSE	Low Side Collector Sense	ī

DBC Substrate

Al₂O₃ isolated substrate, basic isolation, and copper on both sides.

Lead Frame

Copper with Tin electro-plating.

Flammability Information

All materials present in the power module meet UL flammability rating class 94V-0.

MODULE CHARACTERISTICS

Symbol	Parameter				Unit
T _{vj}	Continuous Operating Junction Temperature Range			-40 to 175	°C
T _{STG}	Storage Temperature range			-40 to 125	°C
V _{ISO}	Isolation Voltage, DC, t = 1 s			4200	V
Creepage	Creepage Minimum: Terminal to Terminal				
Clearance	Clearance Minimum: (Note 1) Terminal to Terminal				
CTI	CTI Comparative Tracking Index				
		Min	Тур	Max	
L _{sCE}	Stray Inductance		8		nΗ
R _{CC'+EE'}	R _{CC'+EE'} Module Lead Resistance, Terminals – Chip 0.15				mΩ
G	G Module Weight 75				g
М	M4 Screws for Module Terminals			2.2	Nm

^{1.} Verified by design $\!\!\!/$ not by test.

ABSOLUTE MAXIMUM RATINGS (T_{V,I} = 25°C, unless otherwise specified)

Symbol	Parameter	Rating	Unit
ВТ	•		•
V _{CES}	Collector to Emitter Voltage	750	V
V_{GES}	Gate to Emitter Voltage	±20	V
I _{CN}	Implemented Collector Current	600	Α
I _{C nom}	Continuous DC Collector Current, Tvjmax = 175°C, T _F = 65°C, Ref. Heatsink	500	Α
I _{CRM}	Pulsed Collector Current @ VGE = 15 V, tp = 1 ms	1200	А
ODE			
V_{RRM}	Repetitive Peak Reverse Voltage	750	V
I _{FN}	Implemented Forward Current	600	А
IF	Continuous Forward Current, Tvjmax = 175°C, T _F = 65°C, Ref. Heatsink	400	Α
I _{FRM}	Repetitive Peak Forward Current, t _p = 1 ms	1200	Α
l ² t value	$V_R = 0 \text{ V}, t_p = 10 \text{ ms}, Tv_J = 150^{\circ}\text{C}$ $T_{VJ} = 175^{\circ}\text{C}$	14000 12000	A ² s

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Symbol	Parameter	Min	Тур	Max	Unit
IGBT.R _{th,J-C}	Effective Rth, Junction to Case	-	0.06	0.08	°C/W
IGBT.R _{th,J-F}	Effective Rth, Junction to Fluid, λ_{TIM} = 6 W/m–K, F = 660 N 10 L/min, 65°C, 50/50 EGW, Ref. Heatsink	-	0.146	-	°C/W
Diode.R _{th,J-C}	Effective Rth, Junction to Case	1	0.10	0.13	°C/W
Diode.R _{th,J-F}	Effective Rth, Junction to Fluid, λ_{TIM} = 6 W/m–K, F = 660 N 10 L/min, 65°C, 50/50 EGW, Ref. Heatsink	-	0.196	-	°C/W

CHARACTERISTICS OF IGBT (Tvj = 25° C, unless otherwise specified)

	Parameters Conditions			Min	Тур	Max	unit
V _{CESAT}	Collector to Emitter Saturation Voltage	V _{GE} = 15 V, I _C = 400 A,	$T_{vj} = 25^{\circ}C$ $T_{vj} = 150^{\circ}C$ $T_{vj} = 175^{\circ}C$	- - -	1.23 1.28 1.30	1.35 - -	V
		V _{GE} = 15 V, I _C = 600 A,	T_{vj} = 25°C T_{vj} = 150°C T_{vj} = 175°C	- - -	1.39 1.53 1.57	- - -	
I _{CES}	Collector to Emitter Leakage Current	V _{GE} = 0, V _{CE} = 750 V	T_{vj} = 25°C T_{vj} = 175°C	-	- 8	1 -	mA
I _{GES}	Gate – Emitter Leakage Current	$V_{CE} = 0, V_{GE} = \pm 20 \text{ V}$		-	-	±400	nA
V _{th}	Threshold Voltage	$V_{CE} = V_{GE}, I_{C} = 500 \text{ mA}$		4.5	5.6	6.5	V
Q_{G}	Total Gate Charge	$V_{GE} = -8 \text{ to } 15 \text{ V}, V_{CE} = 40 \text{ I}_{C} = 400 \text{ A}$	00 V,	-	1.0	-	μC
R _{Gint}	Internal Gate Resistance			ı	2	_	Ω
C _{ies}	Input Capacitance	$V_{CE} = 30 \text{ V}, V_{GE} = 0 \text{ V}, f =$	1 MHz	ı	36	_	nF
C _{oes}	Output Capacitance	$V_{CE} = 30 \text{ V}, V_{GE} = 0 \text{ V}, f =$	1 MHz	-	0.7	_	nF
C _{res}	Reverse Transfer Capacitance	$V_{CE} = 30 \text{ V}, V_{GE} = 0 \text{ V}, f =$	1 MHz	-	0.09	_	nF
T _{d.on}	Turn On Delay, Inductive Load	I_C = 400 A, V_{CE} = 400 V V_{GE} = +15/-8 V Rg.on = 3.9 Ω	$T_{vj} = 25^{\circ}C$ $T_{vj} = 150^{\circ}C$ $T_{vj} = 175^{\circ}C$	- - -	194 224 228	-	ns
T _r	Rise Time, Inductive Load	I_C = 400 A, V_{CE} = 400 V V_{GE} = +15/-8 V Rg.on = 3.9 Ω	$T_{vj} = 25^{\circ}C$ $T_{vj} = 150^{\circ}C$ $T_{vj} = 175^{\circ}C$	- - -	71 89 94	- - -	ns
T _{d.off}	Turn Off Delay, Inductive Load	I_C = 400 A, V_{CE} = 400 V V_{GE} = +15/-8 V Rg.off = 15 Ω	$T_{vj} = 25^{\circ}C$ $T_{vj} = 150^{\circ}C$ $T_{vj} = 175^{\circ}C$	- - -	969 1047 1063	- - -	ns
T _f	Fall Time, Inductive Load	I_{C} = 400 A, V_{CE} = 400 V V_{GE} = +15/-8 V Rg.off = 15 Ω	$T_{vj} = 25^{\circ}C$ $T_{vj} = 150^{\circ}C$ $T_{vj} = 175^{\circ}C$	- - -	123 202 230	- - -	ns
E _{ON}	Turn-On Switching Loss (Including Diode Reverse Recovery Loss)	$\begin{array}{l} I_{C} = 400 \text{ A, V}_{CE} = 400 \text{ V} \\ V_{GE} = +15/-8 \text{ V} \\ Rg.on = 3.9 \Omega \\ Ls = 25 \text{ nH} \\ di/dt \left(T_{vj} = 25^{\circ}\text{C}\right) = 4.67 \text{ A/} \\ di/dt \left(T_{vj} = 175^{\circ}\text{C}\right) = 3.61 \text{ A/} \end{array}$		- - -	10.09 16.73 18.57	- - -	mJ
E _{OFF}	Turn-Off SwitchingLoss	$\begin{array}{l} I_{C} = 400 \text{ A, V}_{CE} = 400 \text{ V} \\ V_{GE} = +15/-8 \text{ V} \\ \text{Rg. off} = 15 \Omega \\ \text{Ls} = 25 \text{ nH} \\ \text{dv/dt } (T_{vj} = 25^{\circ}\text{C}) = 2.82 \text{ V/r} \\ \text{dv/dt } (T_{vj} = 175^{\circ}\text{C}) = 2.08 \text{ V/r} \\ \end{array}$	$T_{vj} = 25^{\circ}C$ $T_{vj} = 150^{\circ}C$ $T_{vj} = 175^{\circ}C$ ns //ns	- - -	15.95 25.06 27.30	- - -	mJ
Esc	Minimum Short Circuit Energy Withstand	$V_{GE} \le 15 \text{ V}, V_{CE} = 400 \text{ V}$	T _{vj} = 25°C T _{vj} = 175°C	- 3.5	3.5 -	-	J

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

CHARACTERISTICS OF INVERSE DIODE (Tvj = 25°C, unless otherwise specified)

	Parameters	Conditions		Min	Тур	Max	unit
V _F	Diode Forward Voltage	V _{GE} = 0 V, I _C = 400 A,	$T_{vj} = 25^{\circ}C$ $T_{vj} = 150^{\circ}C$ $T_{vj} = 175^{\circ}C$	- - -	1.34 1.30 1.29	1.47 - -	V
		V _{GE} = 0 V, I _C = 600 A,	$T_{vj} = 25^{\circ}C$ $T_{vj} = 150^{\circ}C$ $T_{vj} = 175^{\circ}C$	1 1 1	1.48 1.47 1.46	1 1	
E _{rr}	Reverse Recovery Energy	$\begin{aligned} &V_{R} = 400 \text{ V, I}_{F} = 400 \text{ A,} \\ &R_{GON} = 3.9 \Omega, \\ &-\text{di/dt} = 3.61 \text{ A/ns (175°C)} \\ &V_{GE} = -8 \text{ V} \end{aligned}$	$T_{vj} = 25^{\circ}C$ $T_{vj} = 150^{\circ}C$ $T_{vj} = 175^{\circ}C$	1 1 1	1.05 4.93 5.90	1 1 1	mJ
Q _{RR}	Recovered Charge	$\begin{aligned} &V_{R} = 400 \text{ V, I}_{F} = 400 \text{ A,} \\ &R_{GON} = 3.9 \Omega, \\ &-\text{di/dt} = 3.61 \text{ A/ns (175°C)} \\ &V_{GE} = -8 \text{ V} \end{aligned}$	$T_{vj} = 25^{\circ}C$ $T_{vj} = 150^{\circ}C$ $T_{vj} = 150^{\circ}C$	- - -	11.60 25.72 29.28		μС
Irr	Peak Reverse Recovery Current	$\begin{aligned} &V_{R} = 400 \text{ V, I}_{F} = 400 \text{ A,} \\ &R_{GON} = 3.9 \Omega, \\ &-\text{di/dt} = 3.61 \text{ A/ns (175°C)} \\ &V_{GE} = -8 \text{ V} \end{aligned}$	$T_{vj} = 25^{\circ}C$ $T_{vj} = 150^{\circ}C$ $T_{vj} = 175^{\circ}C$	- - -	241 294 304	- - -	A

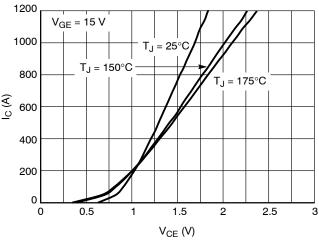
SENSOR CHARACTERISTICS (Tvj = 25°C, unless otherwise specified)

	Parameters Conditions		3	Min	Тур	Max	unit
T _{sense}	Temperature Sense	I _F = 1 mA,	T_{vj} =25°C T_{vj} = 150°C T_{vj} = 175°C	1 1 1	2.5 1.7 1.5	1 1 1	V
I _{sense}	Current Sense	$R_{shunt} = 10 \Omega,$	I _C = 1200 A I _C = 600 A I _C = 100 A	1 1	416 223 50	1 1 1	mV

ORDERING INFORMATION

Part Number	Package	Shipping
NVG600A75L4DSC2	AHPM15-CEA Module Case MODHS (Pb-Free)	18 Units / 3x Tub

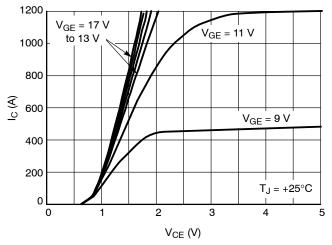
TYPICAL CHARACTERISTICS



1200 $V_{CE} = 20 V$ T_J = 175°C 1000 $T_J = 150^{\circ}C$ 800 600 400 200 __ = 25°C ol 8 10 12 14 6 V_{GE} (V)

Figure 1. IGBT Output Characteristic

Figure 2. IGBT Transfer Characteristic



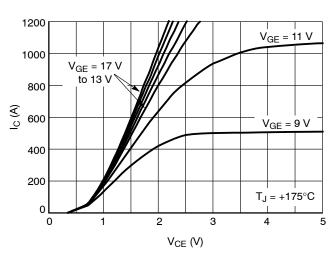
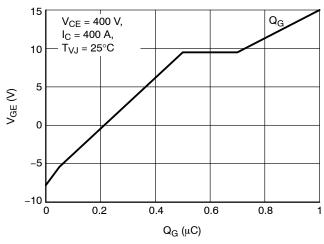


Figure 3. IGBT Output Characteristic, +25°C

Figure 4. IGBT Output Characteristic, +175°C



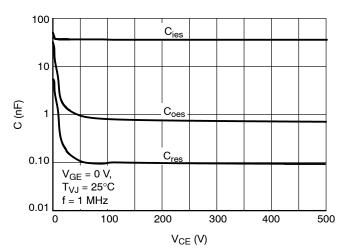
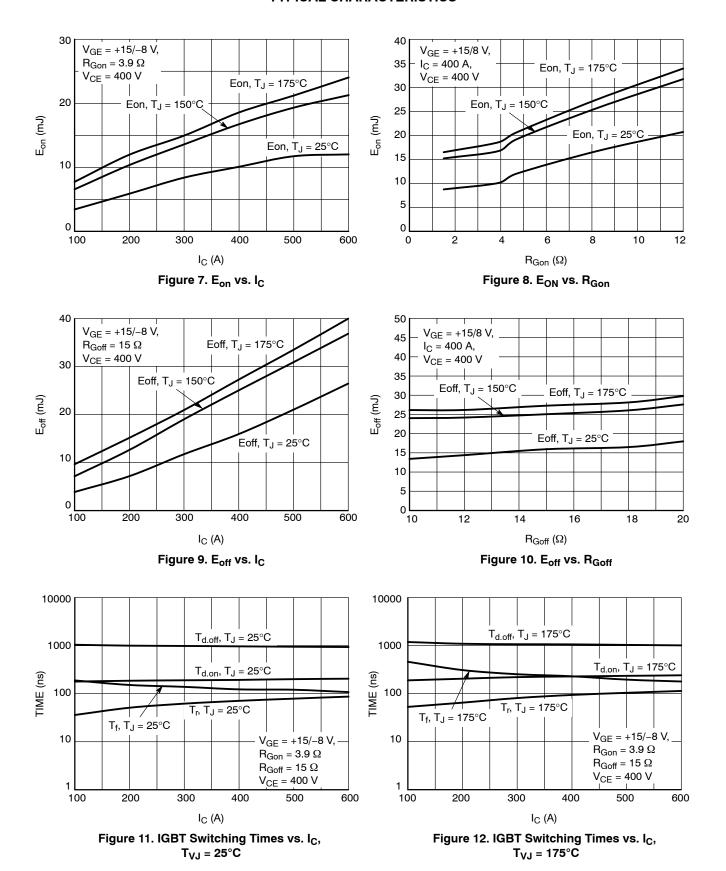


Figure 5. Gate Charge Characteristics

Figure 6. Capacitance Characteristics

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

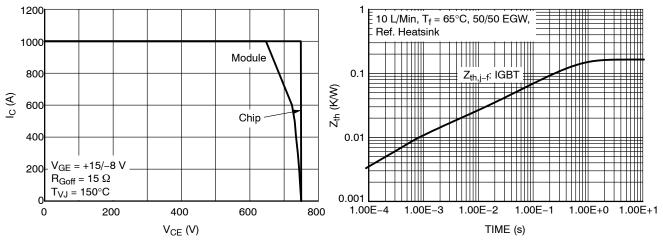


Figure 13. Reverse Bias Safe Operating Area

Figure 14. IGBT Transient Thermal Impedance

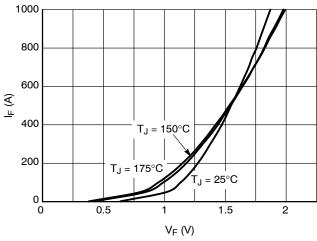


Figure 15. Diode Forward Characteristic

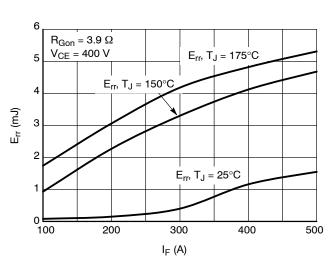


Figure 16. Diode Switching Losses vs. I_F

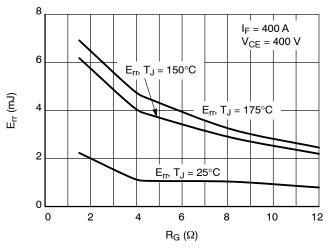


Figure 17. Diode Switching Losses vs. R_{Gon}

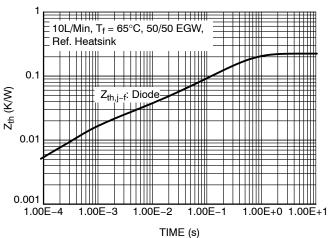
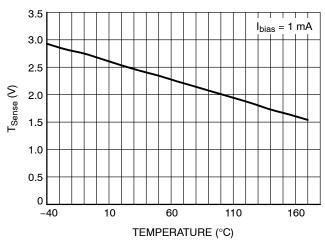


Figure 18. Diode Transient Thermal Impedance

TYPICAL CHARACTERISTICS



600 $R_{shunt} = 10 \Omega$ 175°C 500 150°C 400 I_{Sense} (mV) 25°C 300 200 100 0 700 900 100 300 500 1100 1300 I_C (A)

Figure 19. Temperature Sensor Characteristic

Figure 20. Current Sensor Characteristic

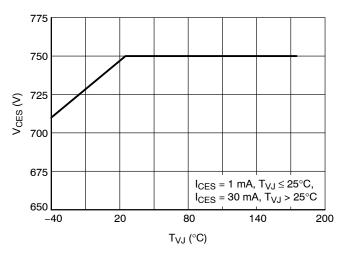


Figure 21. Maximum Allowed V_{CE}

General Note: These are preliminary values measured from a small number of DV units. Values will be updated based on higher quantity of PV measurements.

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